# 2SCR522M / 2SCR522EB / 2SCR522UB

NPN 200mA 20V General Purpose Transistor

**Datasheet** 

Parameter	Value
V <sub>CEO</sub>	20V
I <sub>C</sub>	200mA

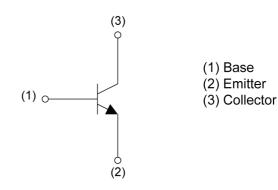
## Outline

SOT-723	SOT-416FL
(1) (2)	(1) (3)
2SCR522M	2SCR522EB
(VMT3)	(EMT3F)
SOT-323FL	
(1) (2)	
2SCR522UB	
(UMT3F)	

## Features

- 1) General Purpose.
- 2) Complementary PNP Types: 2SAR522M (VMT3) / 2SAR522EB (EMT3F) / 2SAR522UB (UMT3F)

## •Inner circuit



# Application

GENERAL PURPOSE SMALL SIGNAL AMPLIFIER

# Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
2SCR522M	SOT-723 (VMT3)	1212	T2L	180	8	8000	NC
2SCR522EB	SOT-416FL (EMT3F)	1616	TL	180	8	3000	NC
2SCR522UB	SOT-323FL (UMT3F)	2021	TL	180	8	3000	NC

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# ● Absolute maximum ratings (T<sub>a</sub> = 25°C)

Parameter			Values	Unit
Collector-base voltage			20	V
Collector-emitter voltage			20	V
Emitter-base voltage			5	V
Calla stan average	I <sub>C</sub>	200	mA	
Collector current		I <sub>CP</sub> *1	400	mA
	2SCR522M		150	
Power dissipation	2SCR522EB	P <sub>D</sub> *2	150	mW
	2SCR522UB		200	
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage tempera	T <sub>stg</sub>	-55 to +150	°C	

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	Curah al	Conditions		Values			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Collector-base breakdown voltage $BV_{CBO}$ $I_C = 50\mu A$		I <sub>C</sub> = 50μA	20	-	-	V	
Collector-emitter breakdown voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 1mA	20	-	-	V	
Emitter-base breakdown voltage	BV <sub>EBO</sub>	I <sub>E</sub> = 50μA	5	1	1	V	
Collector cut-off current	I <sub>CBO</sub>	V <sub>CB</sub> = 20V	-	-	100	nA	
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> = 5V	-	-	100	nA	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> = 100mA, I <sub>B</sub> = 10mA	-	120	300	mV	
DC current gain	h <sub>FE</sub>	V <sub>CE</sub> = 2V, I <sub>C</sub> = 1mA	120	1	560	-	
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> = 10V, I <sub>E</sub> = -10mA, f = 100MHz	-	400	-	MHz	
Output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0A, f = 1MHz	-	2.0	-	pF	

<sup>\*1</sup> Pw=10ms Single Pulse

<sup>\*2</sup> Each terminal mounted on a reference land.

## ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.1 Ground Emitter Propagation
Characteristics

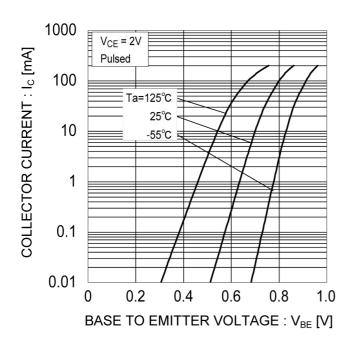


Fig.2 Typical Output Characteristics

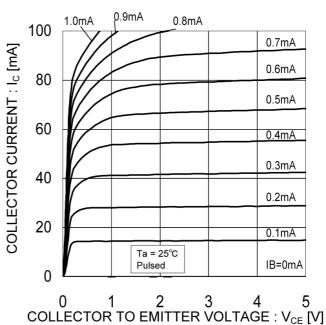


Fig.3 DC Current Gain vs. Collector Current (I)

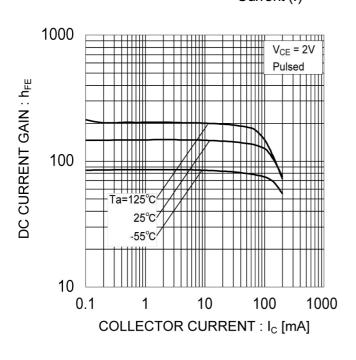
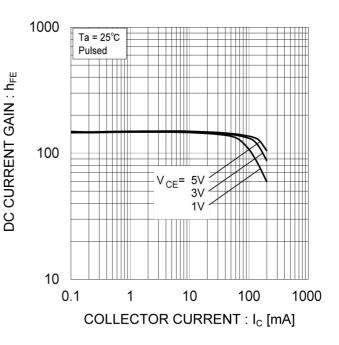


Fig.4 DC Current Gain vs. Collector Current (II)



# ● Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.5 Collector-Emitter Saturation Voltage vs. Collector Current (I)

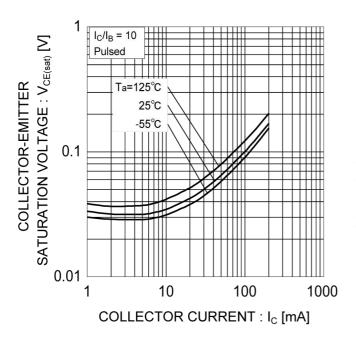


Fig.6 Collector-Emitter Saturation

Voltage vs. Collector Current (II)

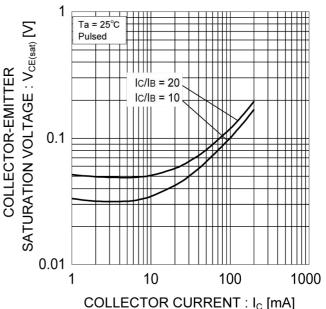


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

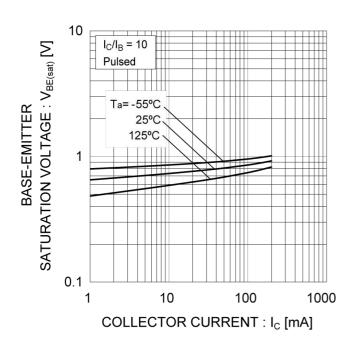
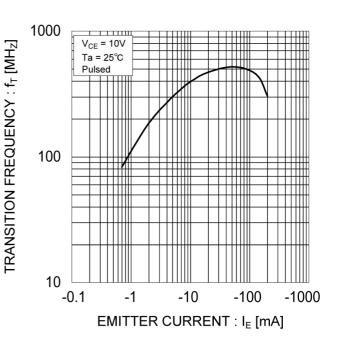


Fig.8 Gain Bandwidth Product vs.

Emitter Current



## ◆Electrical characteristic curves(T<sub>a</sub> = 25°C)

Fig.9 Emitter Input Capacitance vs.
Emitter-Base Voltage
Collector Output Capacitance vs.
Collector-Base Voltage

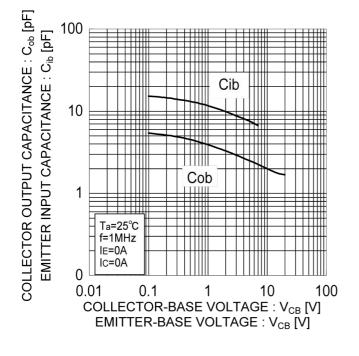


Fig.10 Safe Operating Area

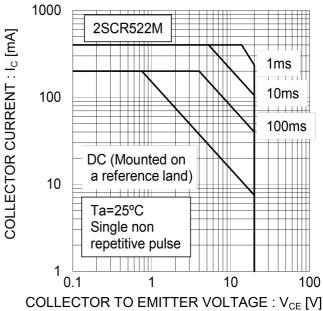


Fig.11 Safe Operating Area

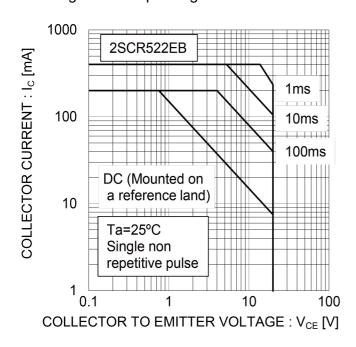
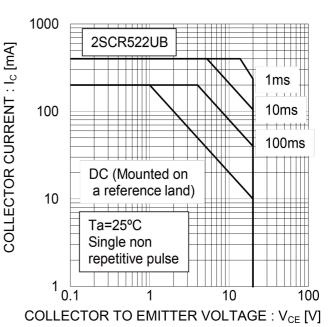
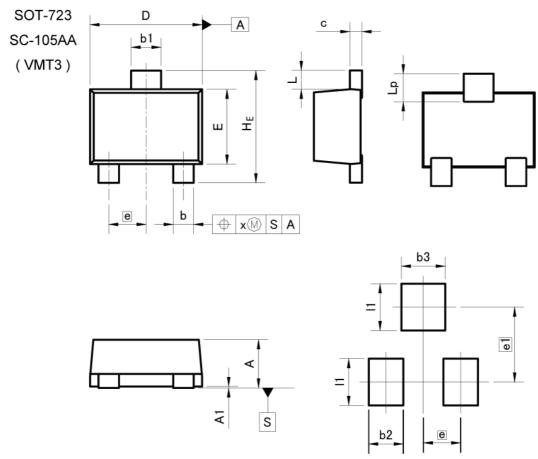


Fig.12 Safe Operating Area



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

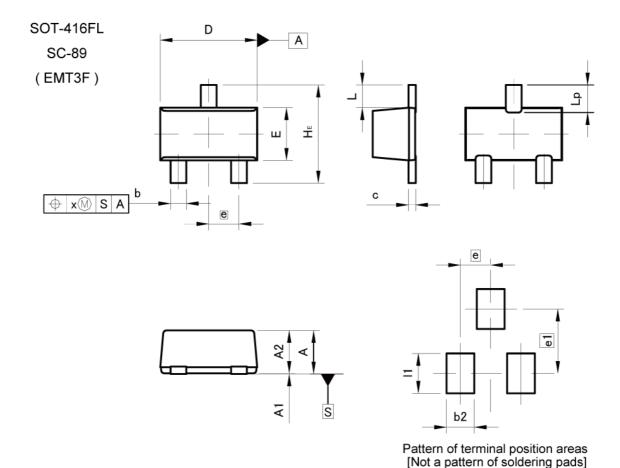
DIM	MILIM	ETERS	INC	HES
DIM [	MIN	MAX	MIN	MAX
Α	0.45	0.55	0.018	0.022
A1	0.00	0.10	0.000	0.004
b	0.17	0.27	0.007	0.011
b1	0.27	0.37	0.011	0.015
С	0.08	0.18	0.003	0.007
D	1.10	1.30	0.043	0.051
E	0.70	0.90	0.028	0.035
е	0.4	40	0.02	
HE	1.10	1.30	0.043	0.051
L	0.10	0.30	0.004	0.012
Lp	0.20	0.40	0.008	0.016
х	#	0.10	<u> </u>	0.004

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b2	<u> </u>	0.37	544	0.015
b3	223	0.47	822	0.019
e1	0.80		0.0	031
11	<del>5</del> 98	0.50	12.50	0.020

Dimension in mm/inches



### Dimensions



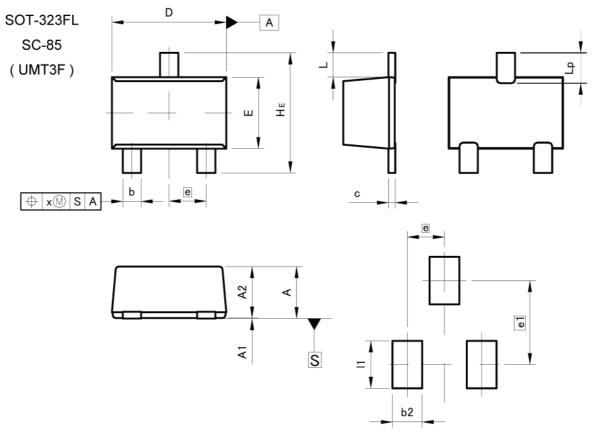
**MILIMETERS INCHES** DIM MIN MAX MIN MAX 0.85 0.033 A 0.65 0.026 A1 0.00 0.10 0.000 0.004 0.60 0.80 0.024 0.031 A2 b 0.21 0.36 0.008 0.014 0.007 0.08 0.18 0.003 C D 1.50 1.70 0.059 0.067 0.76 0.96 0.030 E 0.038 0.50 0.020 е HE 1.50 1.70 0.059 0.067 0.37 0.015 L 0.35 0.55 0.014 0.022 Lp 0.10 0.004 X

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
b2	<del>=</del> 1	0.46	_	0.018
e1	4:	1.05		0.041
11	¥(	0.65	#	0.026

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.85	1.05	0.033	0.041
A1	0.00	0.10	0.000	0.004
A2	0.80	1.00	0.031	0.039
b	0.27	0.42	0.011	0.017
С	0.08	0.18	0.003	0.007
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.0	65	0.026	
HE	2.00	2.20	0.079	0.087
L	0.43		0.0	17
Lp	0.43	0.63	0.017	0.025
х		0.10		0.004

DIM	MILIMETERS		INCHES	
DIM L	MIN	MAX	MIN	MAX
b2	<del>=</del> 8	0.52	-	0.020
e1	1.47		0.0	058
11	_	0.83	-	0.033

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

## **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

## **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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